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Applications of "[Embedded - Microcontrollers](#)"

Details	
Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I ² C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08aw16cfger

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4.2 Register Addresses and Bit Assignments

The registers in the MC9S08AW60 Series are divided into these three groups:

- Direct-page registers are located in the first 112 locations in the memory map, so they are accessible with efficient direct addressing mode instructions.
- High-page registers are used much less often, so they are located above \$1800 in the memory map. This leaves more room in the direct page for more frequently used registers and variables.
- The nonvolatile register area consists of a block of 16 locations in FLASH memory at \$FFB0–\$FFBF.

Nonvolatile register locations include:

- Three values which are loaded into working registers at reset
- An 8-byte backdoor comparison key which optionally allows a user to gain controlled access to secure memory

Because the nonvolatile register locations are FLASH memory, they must be erased and programmed like other FLASH memory locations.

Direct-page registers can be accessed with efficient direct addressing mode instructions. Bit manipulation instructions can be used to access any bit in any direct-page register. Table 4-2 is a summary of all user-accessible direct-page registers and control bits.

The direct page registers in Table 4-2 can use the more efficient direct addressing mode which only requires the lower byte of the address. Because of this, the lower byte of the address in column one is shown in bold text. In Table 4-3 and Table 4-4 the whole address in column one is shown in bold. In Table 4-2, Table 4-3, and Table 4-4, the register names in column two are shown in bold to set them apart from the bit names to the right. Cells that are not associated with named bits are shaded. A shaded cell with a 0 indicates this unused bit always reads as a 0. Shaded cells with dashes indicate unused or reserved bit locations that could read as 1s or 0s.

4.4.1 Features

Features of the FLASH memory include:

- FLASH Size
 - MC9S08AW60 — 63280 bytes (124 pages of 512 bytes each)
 - MC9S08AW48 — 49152 bytes (96 pages of 512 bytes each)
 - MC9S08AW32 — 32768 bytes (64 pages of 512 bytes each)
 - MC9S08AW16 — 16384 bytes (32 pages of 512 bytes each)
- Single power supply program and erase
- Command interface for fast program and erase operation
- Up to 100,000 program/erase cycles at typical voltage and temperature
- Flexible block protection
- Security feature for FLASH and RAM
- Auto power-down for low-frequency read accesses

4.4.2 Program and Erase Times

Before any program or erase command can be accepted, the FLASH clock divider register (FCDIV) must be written to set the internal clock for the FLASH module to a frequency (f_{FCLK}) between 150 kHz and 200 kHz (see Section 4.6.1, “FLASH Clock Divider Register (FCDIV)”). This register can be written only once, so normally this write is done during reset initialization. FCDIV cannot be written if the access error flag, FACCERR in FSTAT, is set. The user must ensure that FACCERR is not set before writing to the FCDIV register. One period of the resulting clock ($1/f_{FCLK}$) is used by the command processor to time program and erase pulses. An integer number of these timing pulses are used by the command processor to complete a program or erase command.

Table 4-5 shows program and erase times. The bus clock frequency and FCDIV determine the frequency of FCLK (f_{FCLK}). The time for one cycle of FCLK is $t_{FCLK} = 1/f_{FCLK}$. The times are shown as a number of cycles of FCLK and as an absolute time for the case where $t_{FCLK} = 5 \mu\text{s}$. Program and erase times shown include overhead for the command state machine and enabling and disabling of program and erase voltages.

Table 4-5. Program and Erase Times

Parameter	Cycles of FCLK	Time if FCLK = 200 kHz
Byte program	9	45 μs
Byte program (burst)	4	20 μs ¹
Page erase	4000	20 ms ²
Mass erase	20,000	100 ms ²

¹ Excluding start/end overhead

² Because the page and mass erase times can be longer than the COP watchdog timeout, the COP should be serviced during any software erase routine.

Table 4-7. FLASH Clock Divider Settings

f_{Bus}	PRDIV8 (Binary)	DIV5:DIV0 (Decimal)	f_{CLK}	Program/Erase Timing Pulse (5 μs Min, 6.7 μs Max)
20 MHz	1	12	192.3 kHz	5.2 μs
10 MHz	0	49	200 kHz	5 μs
8 MHz	0	39	200 kHz	5 μs
4 MHz	0	19	200 kHz	5 μs
2 MHz	0	9	200 kHz	5 μs
1 MHz	0	4	200 kHz	5 μs
200 kHz	0	0	200 kHz	5 μs
150 kHz	0	0	150 kHz	6.7 μs

4.6.2 FLASH Options Register (FOPT and NVOPT)

During reset, the contents of the nonvolatile location NVOPT are copied from FLASH into FOPT. Bits 5 through 2 are not used and always read 0. This register may be read at any time, but writes have no meaning or effect. To change the value in this register, erase and reprogram the NVOPT location in FLASH memory as usual and then issue a new MCU reset.

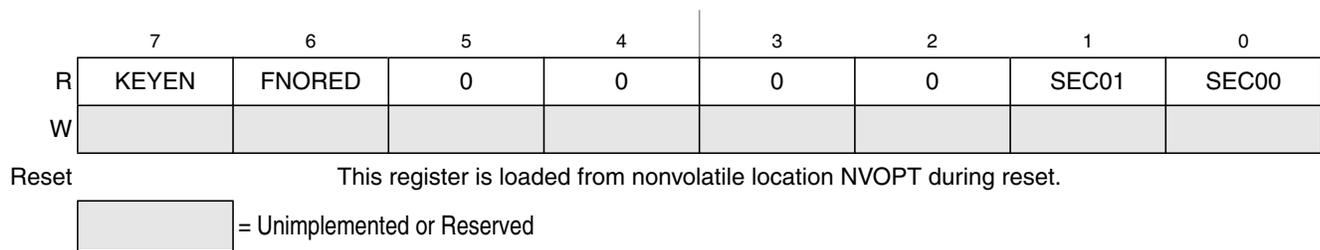


Figure 4-7. FLASH Options Register (FOPT)

Table 4-8. FOPT Register Field Descriptions

Field	Description
7 KEYEN	Backdoor Key Mechanism Enable — When this bit is 0, the backdoor key mechanism cannot be used to disengage security. The backdoor key mechanism is accessible only from user (secured) firmware. BDM commands cannot be used to write key comparison values that would unlock the backdoor key. For more detailed information about the backdoor key mechanism, refer to Section 4.5, “Security.” 0 No backdoor key access allowed. 1 If user firmware writes an 8-byte value that matches the nonvolatile backdoor key (NVBACKKEY through NVBACKKEY+7 in that order), security is temporarily disengaged until the next MCU reset.
6 FNORED	Vector Redirection Disable — When this bit is 1, then vector redirection is disabled. 0 Vector redirection enabled. 1 Vector redirection disabled.
1:0 SEC0[1:0]	Security State Code — This 2-bit field determines the security state of the MCU as shown in Table 4-9. When the MCU is secure, the contents of RAM and FLASH memory cannot be accessed by instructions from any unsecured source including the background debug interface. For more detailed information about security, refer to Section 4.5, “Security.”

- Software-controlled slew rate output buffers
- Eight port A pins
- Eight port B pins shared with ADC1
- Seven port C pins shared with SCI2, IIC1, and MCLK
- Eight port D pins shared with ADC1, KBI1, and TPM1 and TPM2 external clock inputs
- Eight port E pins shared with SCI1, TPM1, and SPI1
- Eight port F pins shared with TPM1 and TPM2
- Seven port G pins shared with XTAL, EXTAL, and KBI1

6.3 Pin Descriptions

The MC9S08AW60 Series has a total of 54 parallel I/O pins in seven ports (PTA–PTG). Not all pins are bonded out in all packages. Consult the pin assignment in Chapter 2, “Pins and Connections,” for available parallel I/O pins. All of these pins are available for general-purpose I/O when they are not used by other on-chip peripheral systems.

After reset, the shared peripheral functions are disabled so that the pins are controlled by the parallel I/O. All of the parallel I/O are configured as inputs (PTxDDn = 0). The pin control functions for each pin are configured as follows: slew rate control enabled (PTxSEn = 1), low drive strength selected (PTxDsn = 0), and internal pullups disabled (PTxPEn = 0).

The following paragraphs discuss each port and the software controls that determine each pin’s use.

6.3.1 Port A

Port A	Bit 7	6	5	4	3	2	1	Bit 0
MCU Pin:	PTA7	PTA6	PTA5	PTA4	PTA3	PTA2	PTA1	PTA0

Figure 6-1. Port A Pin Names

Port A pins are general-purpose I/O pins. Parallel I/O function is controlled by the port A data (PTAD) and data direction (PTADD) registers which are located in page zero register space. The pin control registers, pullup enable (PTAPE), slew rate control (PTASE), and drive strength select (PTADS) are located in the high page registers. Refer to Section 6.4, “Parallel I/O Control” for more information about general-purpose I/O control and Section 6.5, “Pin Control” for more information about pin control.

6.3.2 Port B

Port B	Bit 7	6	5	4	3	2	1	Bit 0
MCU Pin:	PTB7/ AD1P7	PTB6/ AD1P6	PTB5/ AD1P5	PTB4/ AD1P4	PTB3/ AD1P3	PTB2/ AD1P2	PTB1/ AD1P1	PTB0/ AD1P0

Figure 6-2. Port B Pin Names

6.7.7 Port D I/O Registers (PTDD and PTDDD)

Port D parallel I/O function is controlled by the registers listed below.

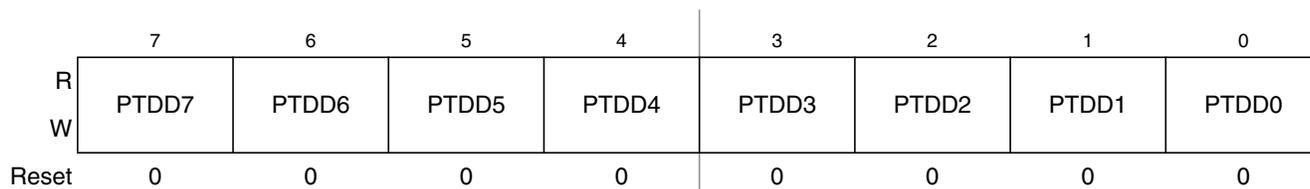


Figure 6-24. Port D Data Register (PTDD)

Table 6-17. PTDD Register Field Descriptions

Field	Description
7:0 PTDD[7:0]	<p>Port D Data Register Bits — For port D pins that are inputs, reads return the logic level on the pin. For port D pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port D pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTDD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pullups disabled.</p>

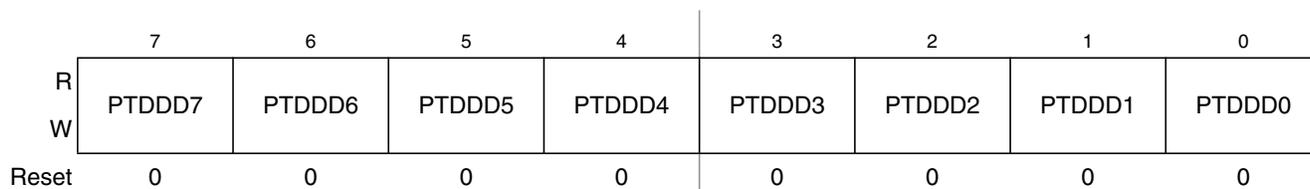


Figure 6-25. Data Direction for Port D (PTDDD)

Table 6-18. PTDDD Register Field Descriptions

Field	Description
7:0 PTDDD[7:0]	<p>Data Direction for Port D Bits — These read/write bits control the direction of port D pins and what is read for PTDD reads.</p> <ul style="list-style-type: none"> 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port D bit n and PTDD reads return the contents of PTDDn.

6.7.9 Port E I/O Registers (PTED and PTEDD)

Port E parallel I/O function is controlled by the registers listed below.

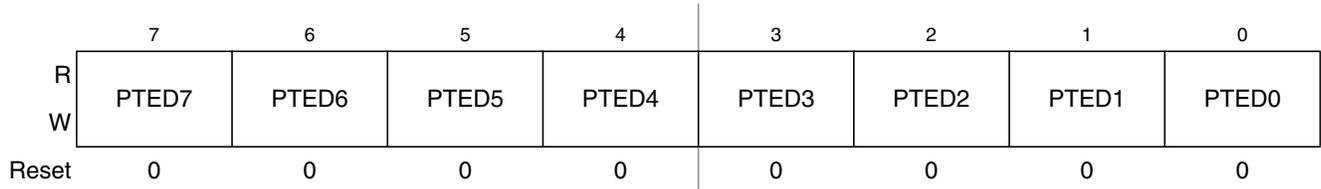


Figure 6-29. Port E Data Register (PTED)

Table 6-22. PTED Register Field Descriptions

Field	Description
7:0 PTED[7:0]	<p>Port E Data Register Bits — For port E pins that are inputs, reads return the logic level on the pin. For port E pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port E pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTED to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pullups disabled.</p>

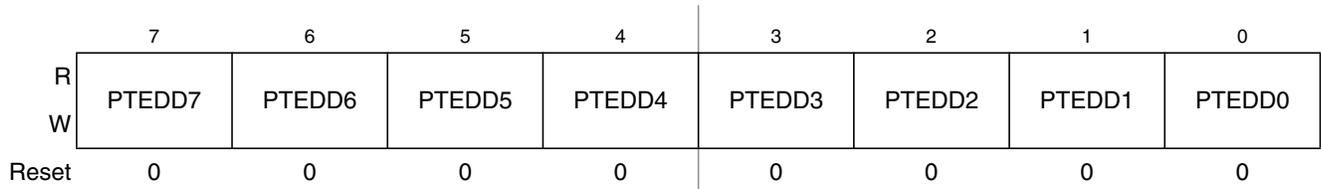


Figure 6-30. Data Direction for Port E (PTEDD)

Table 6-23. PTEDD Register Field Descriptions

Field	Description
7:0 PTEDD[7:0]	<p>Data Direction for Port E Bits — These read/write bits control the direction of port E pins and what is read for PTED reads.</p> <p>0 Input (output driver disabled) and reads return the pin value.</p> <p>1 Output driver enabled for port E bit n and PTED reads return the contents of PTEDn.</p>

6.7.14 Port G Pin Control Registers (PTGPE, PTGSE, PTGDS)

In addition to the I/O control, port G pins are controlled by the registers listed below.

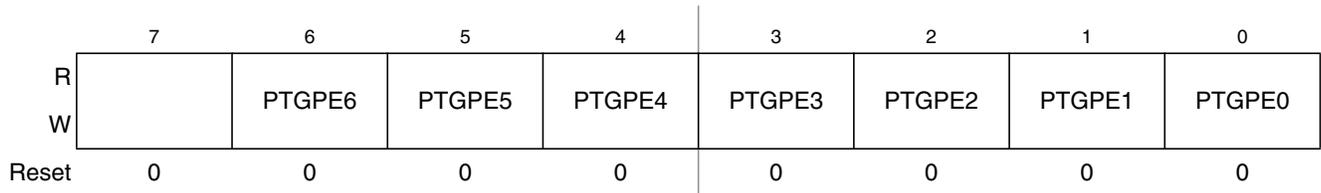


Figure 6-41. Internal Pullup Enable for Port G Bits (PTGPE)

Table 6-34. PTGPE Register Field Descriptions

Field	Description
6:0 PTGPE[6:0]	<p>Internal Pullup Enable for Port G Bits — Each of these control bits determines if the internal pullup device is enabled for the associated PTG pin. For port G pins that are configured as outputs, these bits have no effect and the internal pullup devices are disabled.</p> <p>0 Internal pullup device disabled for port G bit n. 1 Internal pullup device enabled for port G bit n.</p>

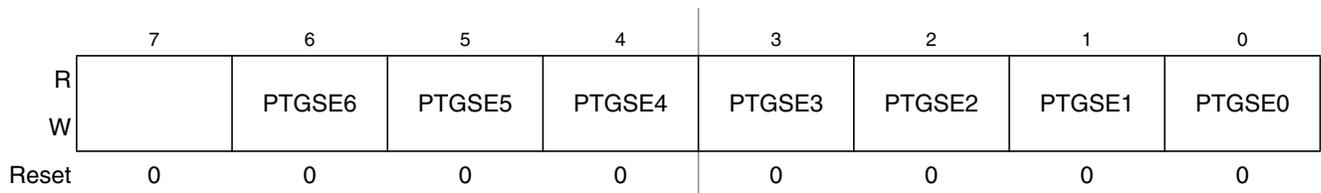


Figure 6-42. Output Slew Rate Control Enable for Port G Bits (PTGSE)

Table 6-35. PTGSE Register Field Descriptions

Field	Description
6:0 PTGSE[6:0]	<p>Output Slew Rate Control Enable for Port G Bits— Each of these control bits determine whether output slew rate control is enabled for the associated PTG pin. For port G pins that are configured as inputs, these bits have no effect.</p> <p>0 Output slew rate control disabled for port G bit n. 1 Output slew rate control enabled for port G bit n.</p>

- 0 = Bit forced to 0
- 1 = Bit forced to 1
- = Bit set or cleared according to results of operation
- U = Undefined after the operation

Machine coding notation

- dd = Low-order 8 bits of a direct address 0x0000–0x00FF (high byte assumed to be 0x00)
- ee = Upper 8 bits of 16-bit offset
- ff = Lower 8 bits of 16-bit offset or 8-bit offset
- ii = One byte of immediate data
- jj = High-order byte of a 16-bit immediate data value
- kk = Low-order byte of a 16-bit immediate data value
- hh = High-order byte of 16-bit extended address
- ll = Low-order byte of 16-bit extended address
- rr = Relative offset

Source form

Everything in the source forms columns, *except expressions in italic characters*, is literal information that must appear in the assembly source file exactly as shown. The initial 3- to 5-letter mnemonic is always a literal expression. All commas, pound signs (#), parentheses, and plus signs (+) are literal characters.

- n* — Any label or expression that evaluates to a single integer in the range 0–7
- opr8i* — Any label or expression that evaluates to an 8-bit immediate value
- opr16i* — Any label or expression that evaluates to a 16-bit immediate value
- opr8a* — Any label or expression that evaluates to an 8-bit value. The instruction treats this 8-bit value as the low order 8 bits of an address in the direct page of the 64-Kbyte address space (0x00xx).
- opr16a* — Any label or expression that evaluates to a 16-bit value. The instruction treats this value as an address in the 64-Kbyte address space.
- opr8* — Any label or expression that evaluates to an unsigned 8-bit value, used for indexed addressing
- opr16* — Any label or expression that evaluates to a 16-bit value. Because the HCS08 has a 16-bit address bus, this can be either a signed or an unsigned value.
- rel* — Any label or expression that refers to an address that is within –128 to +127 locations from the next address after the last byte of object code for the current instruction. The assembler will calculate the 8-bit signed offset and include it in the object code for this instruction.

Address modes

- INH = Inherent (no operands)
- IMM = 8-bit or 16-bit immediate
- DIR = 8-bit direct
- EXT = 16-bit extended

9.4.1 KBI Status and Control Register (KBI1SC)

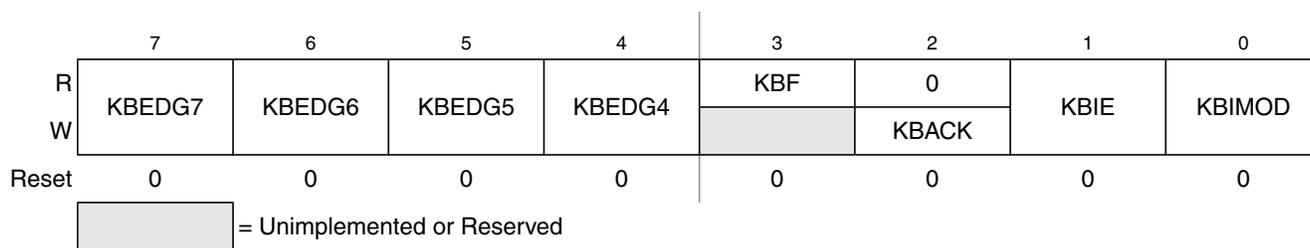


Figure 9-3. KBI Status and Control Register (KBI1SC)

Table 9-2. KBI1SC Register Field Descriptions

Field	Description
7:4 KBEDG[7:4]	Keyboard Edge Select for KBI Port Bits — Each of these read/write bits selects the polarity of the edges and/or levels that are recognized as trigger events on the corresponding KBI port pin when it is configured as a keyboard interrupt input (KBIPE _n = 1). Also see the KBIMOD control bit, which determines whether the pin is sensitive to edges-only or edges and levels. 0 Falling edges/low levels 1 Rising edges/high levels
3 KBF	Keyboard Interrupt Flag — This read-only status flag is set whenever the selected edge event has been detected on any of the enabled KBI port pins. This flag is cleared by writing a 1 to the KBACK control bit. The flag will remain set if KBIMOD = 1 to select edge-and-level operation and any enabled KBI port pin remains at the asserted level. KBF can be used as a software pollable flag (KBIE = 0) or it can generate a hardware interrupt request to the CPU (KBIE = 1). 0 No KBI interrupt pending 1 KBI interrupt pending
2 KBACK	Keyboard Interrupt Acknowledge — This write-only bit (reads always return 0) is used to clear the KBF status flag by writing a 1 to KBACK. When KBIMOD = 1 to select edge-and-level operation and any enabled KBI port pin remains at the asserted level, KBF is being continuously set so writing 1 to KBACK does not clear the KBF flag.
1 KBIE	Keyboard Interrupt Enable — This read/write control bit determines whether hardware interrupts are generated when the KBF status flag equals 1. When KBIE = 0, no hardware interrupts are generated, but KBF can still be used for software polling. 0 KBF does not generate hardware interrupts (use polling) 1 KBI hardware interrupt requested when KBF = 1
KBIMOD	Keyboard Detection Mode — This read/write control bit selects either edge-only detection or edge-and-level detection. KBI port bits 3 through 0 can detect falling edges-only or falling edges and low levels. KBI port bits 7 through 4 can be configured to detect either: <ul style="list-style-type: none"> • Rising edges-only or rising edges and high levels (KBEDG_n = 1) • Falling edges-only or falling edges and low levels (KBEDG_n = 0) 0 Edge-only detection 1 Edge-and-level detection

Table 11-5. SCIxS1 Register Field Descriptions (continued)

Field	Description
5 RDRF	<p>Receive Data Register Full Flag — RDRF becomes set when a character transfers from the receive shifter into the receive data register (SCIxD). In 8-bit mode, to clear RDRF, read SCIxS1 with RDRF = 1 and then read the SCI data register (SCIxD). In 9-bit mode, to clear RDRF, read SCIxS1 with RDRF = 1 and then read SCIxD and the SCI control 3 register (SCIxC3). SCIxD and SCIxC3 can be read in any order, but the flag is cleared only after both data registers are read.</p> <p>0 Receive data register empty. 1 Receive data register full.</p>
4 IDLE	<p>Idle Line Flag — IDLE is set when the SCI receive line becomes idle for a full character time after a period of activity. When ILT = 0, the receiver starts counting idle bit times after the start bit. So if the receive character is all 1s, these bit times and the stop bit time count toward the full character time of logic high (10 or 11 bit times depending on the M control bit) needed for the receiver to detect an idle line. When ILT = 1, the receiver doesn't start counting idle bit times until after the stop bit. So the stop bit and any logic high bit times at the end of the previous character do not count toward the full character time of logic high needed for the receiver to detect an idle line.</p> <p>To clear IDLE, read SCIxS1 with IDLE = 1 and then read the SCI data register (SCIxD). After IDLE has been cleared, it cannot become set again until after a new character has been received and RDRF has been set. IDLE will get set only once even if the receive line remains idle for an extended period.</p> <p>0 No idle line detected. 1 Idle line was detected.</p>
3 OR	<p>Receiver Overrun Flag — OR is set when a new serial character is ready to be transferred to the receive data register (buffer), but the previously received character has not been read from SCIxD yet. In this case, the new character (and all associated error information) is lost because there is no room to move it into SCIxD. To clear OR, read SCIxS1 with OR = 1 and then read the SCI data register (SCIxD).</p> <p>0 No overrun. 1 Receive overrun (new SCI data lost).</p>
2 NF	<p>Noise Flag — The advanced sampling technique used in the receiver takes seven samples during the start bit and three samples in each data bit and the stop bit. If any of these samples disagrees with the rest of the samples within any bit time in the frame, the flag NF will be set at the same time as the flag RDRF gets set for the character. To clear NF, read SCIxS1 and then read the SCI data register (SCIxD).</p> <p>0 No noise detected. 1 Noise detected in the received character in SCIxD.</p>
1 FE	<p>Framing Error Flag — FE is set at the same time as RDRF when the receiver detects a logic 0 where the stop bit was expected. This suggests the receiver was not properly aligned to a character frame. To clear FE, read SCIxS1 with FE = 1 and then read the SCI data register (SCIxD).</p> <p>0 No framing error detected. This does not guarantee the framing is correct. 1 Framing error.</p>
0 PF	<p>Parity Error Flag — PF is set at the same time as RDRF when parity is enabled (PE = 1) and the parity bit in the received character does not agree with the expected parity value. To clear PF, read SCIxS1 and then read the SCI data register (SCIxD).</p> <p>0 No parity error. 1 Parity error.</p>

Table 12-7. SPI1S Register Field Descriptions

Field	Description
7 SPRF	<p>SPI Read Buffer Full Flag — SPRF is set at the completion of an SPI transfer to indicate that received data may be read from the SPI data register (SPI1D). SPRF is cleared by reading SPRF while it is set, then reading the SPI data register.</p> <p>0 No data available in the receive data buffer 1 Data available in the receive data buffer</p>
5 SPTEF	<p>SPI Transmit Buffer Empty Flag — This bit is set when there is room in the transmit data buffer. It is cleared by reading SPI1S with SPTEF set, followed by writing a data value to the transmit buffer at SPI1D. SPI1S must be read with SPTEF = 1 before writing data to SPI1D or the SPI1D write will be ignored. SPTEF generates an SPTEF CPU interrupt request if the SPTIE bit in the SPI1C1 is also set. SPTEF is automatically set when a data byte transfers from the transmit buffer into the transmit shift register. For an idle SPI (no data in the transmit buffer or the shift register and no transfer in progress), data written to SPI1D is transferred to the shifter almost immediately so SPTEF is set within two bus cycles allowing a second 8-bit data value to be queued into the transmit buffer. After completion of the transfer of the value in the shift register, the queued value from the transmit buffer will automatically move to the shifter and SPTEF will be set to indicate there is room for new data in the transmit buffer. If no new data is waiting in the transmit buffer, SPTEF simply remains set and no data moves from the buffer to the shifter.</p> <p>0 SPI transmit buffer not empty 1 SPI transmit buffer empty</p>
4 MODF	<p>Master Mode Fault Flag — MODF is set if the SPI is configured as a master and the slave select input goes low, indicating some other SPI device is also configured as a master. The \overline{SS} pin acts as a mode fault error input only when MSTR = 1, MODFEN = 1, and SSOE = 0; otherwise, MODF will never be set. MODF is cleared by reading MODF while it is 1, then writing to SPI control register 1 (SPI1C1).</p> <p>0 No mode fault error 1 Mode fault error detected</p>

12.3.5 SPI Data Register (SPI1D)

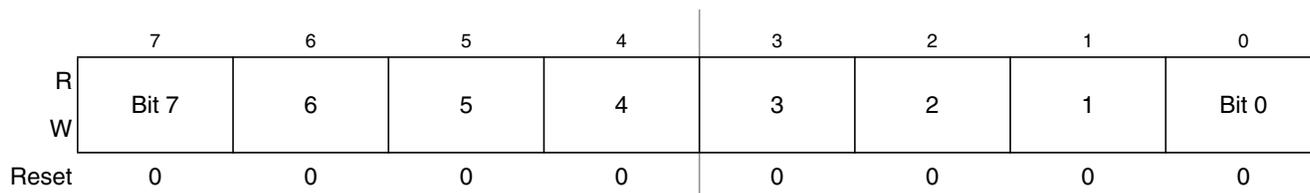


Figure 12-9. SPI Data Register (SPI1D)

Reads of this register return the data read from the receive data buffer. Writes to this register write data to the transmit data buffer. When the SPI is configured as a master, writing data to the transmit data buffer initiates an SPI transfer.

Data should not be written to the transmit data buffer unless the SPI transmit buffer empty flag (SPTEF) is set, indicating there is room in the transmit buffer to queue a new transmit byte.

Data may be read from SPI1D any time after SPRF is set and before another transfer is finished. Failure to read the data out of the receive data buffer before a new transfer ends causes a receive overrun condition and the data from the new transfer is lost.

in LSBFE. Both variations of SPSCCK polarity are shown, but only one of these waveforms applies for a specific transfer, depending on the value in CPOL. The SAMPLE IN waveform applies to the MOSI input of a slave or the MISO input of a master. The MOSI waveform applies to the MOSI output pin from a master and the MISO waveform applies to the MISO output from a slave. The \overline{SS} OUT waveform applies to the slave select output from a master (provided MODFEN and SSOE = 1). The master \overline{SS} output goes to active low at the start of the first bit time of the transfer and goes back high one-half SPSCCK cycle after the end of the eighth bit time of the transfer. The \overline{SS} IN waveform applies to the slave select input of a slave.

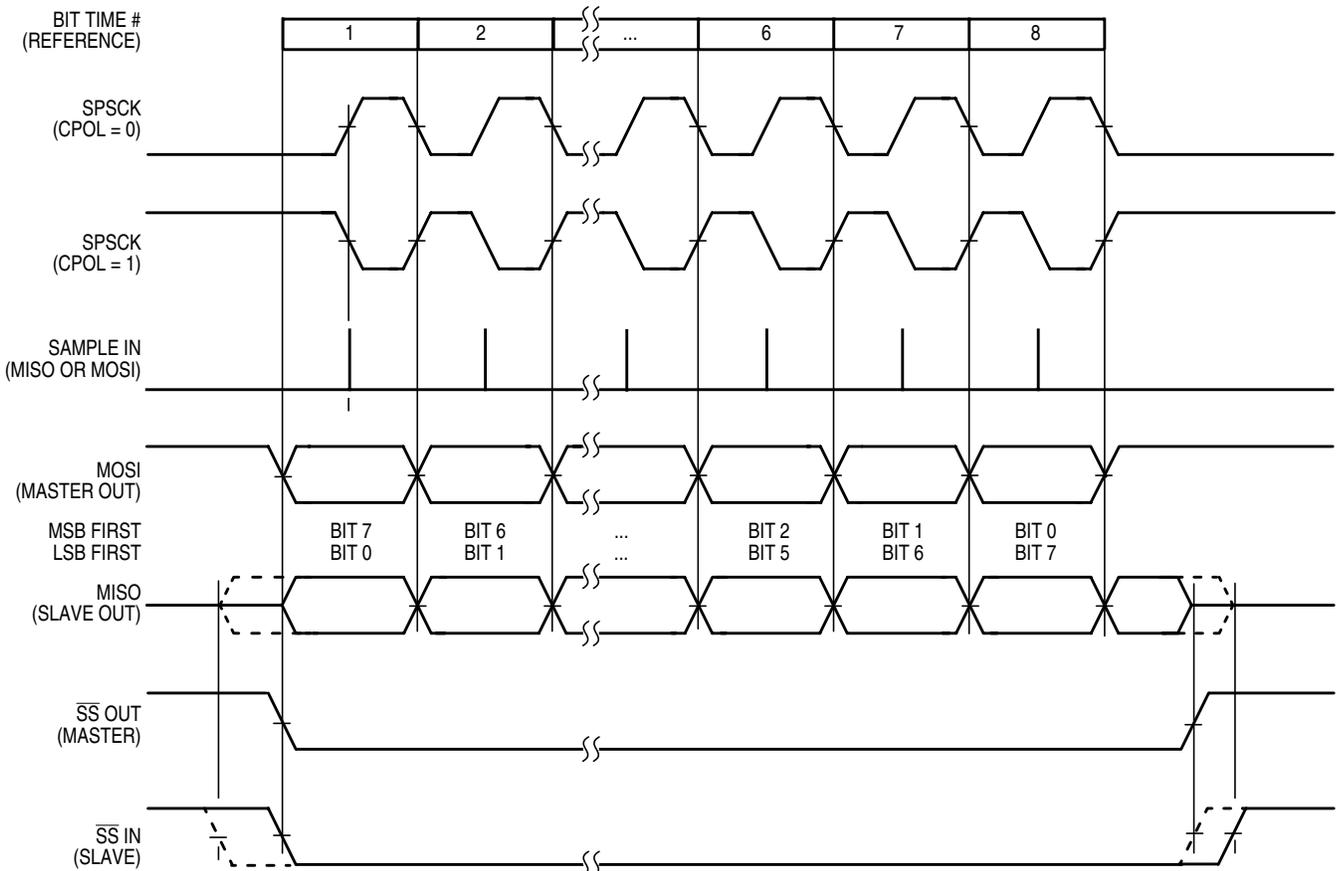


Figure 12-11. SPI Clock Formats (CPHA = 0)

When CPHA = 0, the slave begins to drive its MISO output with the first data bit value (MSB or LSB depending on LSBFE) when \overline{SS} goes to active low. The first SPSCCK edge causes both the master and the slave to sample the data bit values on their MISO and MOSI inputs, respectively. At the second SPSCCK edge, the SPI shifter shifts one bit position which shifts in the bit value that was just sampled and shifts the second data bit value out the other end of the shifter to the MOSI and MISO outputs of the master and slave, respectively. When CPHA = 0, the slave's \overline{SS} input must go to its inactive high level between transfers.

13.3.3 IIC Control Register (IIC1C)

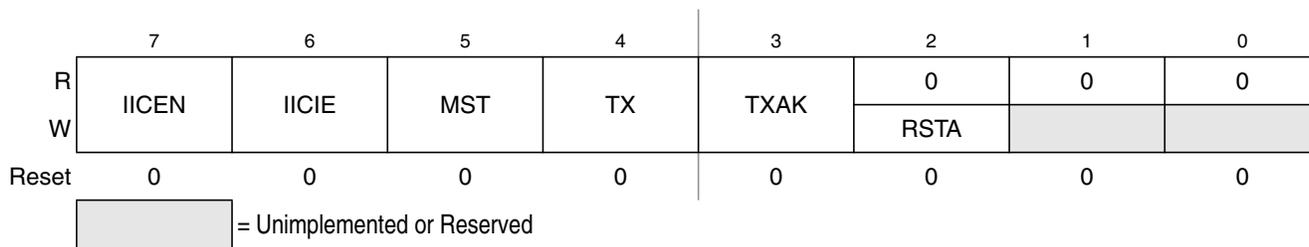


Figure 13-5. IIC Control Register (IIC1C)

Table 13-4. IIC1C Register Field Descriptions

Field	Description
7 IICEN	IIC Enable — The IICEN bit determines whether the IIC module is enabled. 0 IIC is not enabled. 1 IIC is enabled.
6 IICIE	IIC Interrupt Enable — The IICIE bit determines whether an IIC interrupt is requested. 0 IIC interrupt request not enabled. 1 IIC interrupt request enabled.
5 MST	Master Mode Select — The MST bit is changed from a 0 to a 1 when a START signal is generated on the bus and master mode is selected. When this bit changes from a 1 to a 0 a STOP signal is generated and the mode of operation changes from master to slave. 0 Slave Mode. 1 Master Mode.
4 TX	Transmit Mode Select — The TX bit selects the direction of master and slave transfers. In master mode this bit should be set according to the type of transfer required. Therefore, for address cycles, this bit will always be high. When addressed as a slave this bit should be set by software according to the SRW bit in the status register. 0 Receive. 1 Transmit.
3 TXAK	Transmit Acknowledge Enable — This bit specifies the value driven onto the SDA during data acknowledge cycles for both master and slave receivers. 0 An acknowledge signal will be sent out to the bus after receiving one data byte. 1 No acknowledge signal response is sent.
2 RSTA	Repeat START — Writing a one to this bit will generate a repeated START condition provided it is the current master. This bit will always be read as a low. Attempting a repeat at the wrong time will result in loss of arbitration.

A force-type breakpoint waits for the current instruction to finish and then acts upon the breakpoint request. The usual action in response to a breakpoint is to go to active background mode rather than continuing to the next instruction in the user application program.

The tag vs. force terminology is used in two contexts within the debug module. The first context refers to breakpoint requests from the debug module to the CPU. The second refers to match signals from the comparators to the debugger control logic. When a tag-type break request is sent to the CPU, a signal is entered into the instruction queue along with the opcode so that if/when this opcode ever executes, the CPU will effectively replace the tagged opcode with a BGND opcode so the CPU goes to active background mode rather than executing the tagged instruction. When the TRGSEL control bit in the DBGTC register is set to select tag-type operation, the output from comparator A or B is qualified by a block of logic in the debug module that tracks opcodes and only produces a trigger to the debugger if the opcode at the compare address is actually executed. There is separate opcode tracking logic for each comparator so more than one compare event can be tracked through the instruction queue at a time.

15.3.5 Trigger Modes

The trigger mode controls the overall behavior of a debug run. The 4-bit TRG field in the DBGTC register selects one of nine trigger modes. When TRGSEL = 1 in the DBGTC register, the output of the comparator must propagate through an opcode tracking circuit before triggering FIFO actions. The BEGIN bit in DBGTC chooses whether the FIFO begins storing data when the qualified trigger is detected (begin trace), or the FIFO stores data in a circular fashion from the time it is armed until the qualified trigger is detected (end trigger).

A debug run is started by writing a 1 to the ARM bit in the DBGTC register, which sets the ARMF flag and clears the AF and BF flags and the CNT bits in DBGSR. A begin-trace debug run ends when the FIFO gets full. An end-trace run ends when the selected trigger event occurs. Any debug run can be stopped manually by writing a 0 to ARM or DBGGEN in DBGTC.

In all trigger modes except event-only modes, the FIFO stores change-of-flow addresses. In event-only trigger modes, the FIFO stores data in the low-order eight bits of the FIFO.

The BEGIN control bit is ignored in event-only trigger modes and all such debug runs are begin type traces. When TRGSEL = 1 to select opcode fetch triggers, it is not necessary to use R/W in comparisons because opcode tags would only apply to opcode fetches that are always read cycles. It would also be unusual to specify TRGSEL = 1 while using a full mode trigger because the opcode value is normally known at a particular address.

The following trigger mode descriptions only state the primary comparator conditions that lead to a trigger. Either comparator can usually be further qualified with R/W by setting RWAEN (RWBEN) and the corresponding RWA (RWB) value to be matched against R/W. The signal from the comparator with optional R/W qualification is used to request a CPU breakpoint if BRKEN = 1 and TAG determines whether the CPU request will be a tag request or a force request.

Appendix A

Electrical Characteristics and Timing Specifications

A.1 Introduction

This section contains electrical and timing specifications.

A.2 Parameter Classification

The electrical parameters shown in this supplement are guaranteed by various methods. To give you a better understanding, the following classification is used and the parameters are tagged accordingly in the tables where appropriate:

Table A-1. Parameter Classifications

P	Those parameters are guaranteed during production testing on each individual device.
C	Those parameters are achieved by the design characterization by measuring a statistically relevant sample size across process variations.
T	Those parameters are achieved by design characterization on a small sample size from typical devices under typical conditions unless otherwise noted. All values shown in the typical column are within this category.
D	Those parameters are derived mainly from simulations.

NOTE

The classification is shown in the column labeled “C” in the parameter tables where appropriate.

A.3 Absolute Maximum Ratings

Absolute maximum ratings are stress ratings only, and functional operation at the maxima is not guaranteed. Stress beyond the limits specified in Table A-2 may affect device reliability or cause permanent damage to the device. For functional operating conditions, refer to the remaining tables in this section.

This device contains circuitry protecting against damage due to high static voltage or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (for instance, either V_{SS} or V_{DD}).

A.6 DC Characteristics

This section includes information about power supply requirements, I/O pin characteristics, and power supply current in various operating modes.

Table A-6. MCU Operating Conditions

Characteristic	Min	Typ	Max	Unit
Supply Voltage	2.7	—	5.5	V
Temperature				°C
M	-40	—	125	
V	-40	—	105	
C	-40	—	85	

Table A-7. DC Characteristics

Num	C	Parameter	Symbol	Min	Typ ¹	Max	Unit
1	P	Output high voltage — Low Drive (PTxDSn = 0) 5 V, I _{Load} = -2 mA 3 V, I _{Load} = -0.6 mA 5 V, I _{Load} = -0.4 mA 3 V, I _{Load} = -0.24 mA	V _{OH}	V _{DD} - 1.5	—	—	V
		V _{DD} - 1.5		—	—		
2	P	Output high voltage — High Drive (PTxDSn = 1) 5 V, I _{Load} = -10 mA 3 V, I _{Load} = -3 mA 5 V, I _{Load} = -2 mA 3 V, I _{Load} = -0.4 mA	V _{OH}	V _{DD} - 1.5	—	—	V
		V _{DD} - 1.5		—	—		
3	D	Output low voltage — Low Drive (PTxDSn = 0) 5 V, I _{Load} = 2 mA 3 V, I _{Load} = 0.6 mA 5 V, I _{Load} = 0.4 mA 3 V, I _{Load} = 0.24 mA	V _{OL}	—	—	1.5	V
		—		—	1.5		
4	P	Output low voltage — High Drive (PTxDSn = 1) 5 V, I _{Load} = 10 mA 3 V, I _{Load} = 3 mA 5 V, I _{Load} = 2 mA 3 V, I _{Load} = 0.4 mA	V _{OL}	—	—	1.5	V
		—		—	1.5		
5	D	Output high current — Max total I _{OH} for all ports 5V 3V	I _{OHT}	— —	— —	100 60	mA
6	D	Output low current — Max total I _{OL} for all ports 5V 3V	I _{OLT}	— —	— —	100 60	mA
7	P	Input high voltage; all digital inputs	V _{IH}	0.65 × V _{DD}	—	—	V
8	P	Input low voltage; all digital inputs	V _{IL}	—	—	0.35 × V _{DD}	
9	T	Input hysteresis; all digital inputs	V _{hys}	0.06 × V _{DD}			mV
10	P	Input leakage current; input only pins ²	I _{In}	—	0.01	1	μA